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## DESCRIPTION OF DRAWINGS

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### [Brief Description of the Drawings]

[Drawing 1] It is a front view showing the jointing condition of two semiconductor substrates by one example of this invention.

[Drawing 2] It is a front view showing the jointing condition of two semiconductor substrates by other examples of this invention.

[Drawing 3] It is a perspective view showing the example of 1 composition of the sensor body of the gas flow sensor formed by micro-machining processing of a semiconductor substrate.

[Drawing 4] It is a top view of the bottom semiconductor substrate in the sensor body shown in drawing 3.

[Drawing 5] It is a right sectional view of the sensor body shown in drawing 3.

[Drawing 6] It is a front view showing an example of the jointing condition in the case of joining the bottom semiconductor substrate and upper part semiconductor substrate in a sensor body of a gas rate sensor by this invention.

[Drawing 7] It is a front view showing the jointing condition of two conventional semiconductor substrates.

### [Description of Notations]

1 Si semiconductor substrate

2 Si semiconductor substrate

3 A general semiconductor substrate

4 A general semiconductor substrate

5 Bottom semiconductor substrate

6 Upper part semiconductor substrate

7 Nozzle hole

8 Gas passageway

91 Heat wire

92 Heat wire

[Translation done.]